

## ABSTRACT OF THE DISCLOSURE

A packaging fabrication for an organic electroluminescence panel is disclosed. The panel comprises a printed circuit board, one or a plurality of OEL panels and a plurality of bumps, wherein the OEL is provided with poly solder interconnections in area array. The printed circuit board is provided with a plurality of solder pads arranged with bumps. One or a plurality of OEL is arranged on the printed circuit board and the poly solder interconnections and bumps are used to electrically connect the OEL with the printed circuit board. Further, the excellent heat dissipation property of the low re-flow temperature of the poly solder interconnections and the ceramic printed circuit board provides packaging fabrication for low temperature low stress OEL.